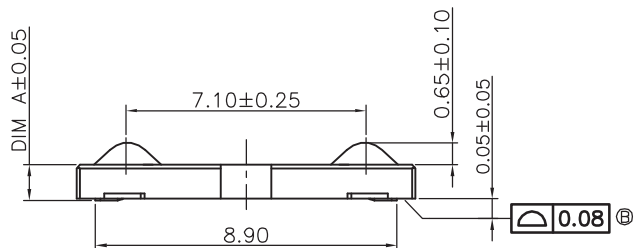
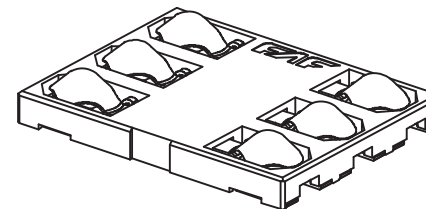
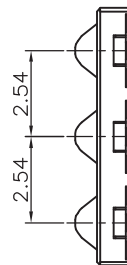
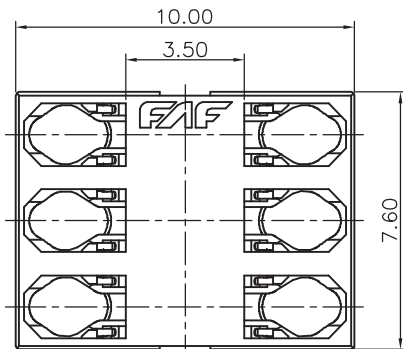


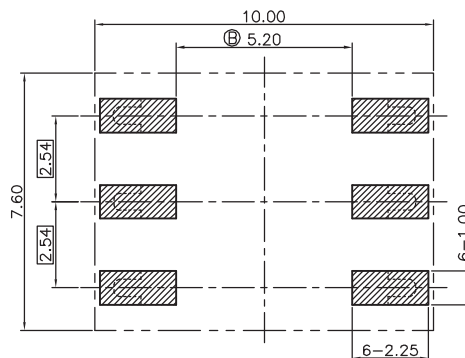
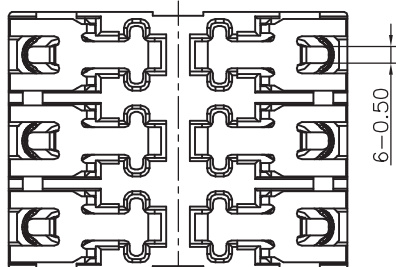
A3

REV	ECN NO	DESCRIPTION	DATE	APPD
A	ECN1210014	NEW RELEASE	2012.10.22	BILL
B		CHANGE DIMENSION	2012.11.10	BILL



NOTES:

- MATERIAL:
 - HOUSING: HIGH TEMP. PLASTIC,UL94-V0
 - CONTACT: COPPER ALLOY
- FINISH:
 - CONTACT: CONTACT AREA: Au PLATED OVER Ni PLATED OVER ALL SOLDER AREA: GOLD FLASH
- ELECTRICAL CHARACTERISTICS:
 - CONTACT CURRENT RATING: 1.0A MAX.
 - CONTACT RESISTANCE: 50 mOHMS MAX.
 - INSULATION RESISTANCE: 1000 MOHMS MIN.
- MECHANICAL CHARACTERISTICS:
 - NORMAL FORCE: 50gf MIN./PIN
 - DURABILITY : 5000 CYCLES
- ENVIRONMENT CHARACTERISTICS:
 - OPERATING TEMPERATURE: -25°C~85°C
 - STORAGE TEMPERATURE: -40°C~85°C
- RECOMMENDED IR REFLOW PROCESS PEAK TEMPERATURE: 260°C MAX, TIME 10s
- ALL SMT CONTACTS AND PADS CO-PLANARITY: 0.10mm MAX



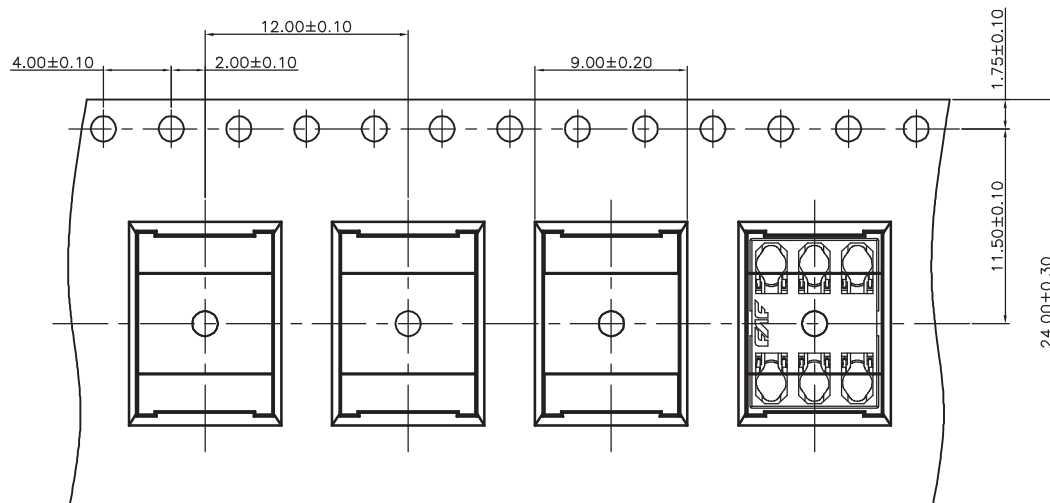
RECOMMENDED PCB LAYOUT
TOLERANCES ±0.05

EXTEND USE		TITLE		FAF.	
SIM CARD CONN.		LOW PROFILE SIM CARD CUSTOMER DRAWING		DWG NO	
GENERAL TOLERANCE		MATERIAL		C-1.029A0	
DIMENSION		QTY		P/N:	
ANGLES		FINISHED		SEE TABLE	
PART NO.		SHEET		SCALE	
DIM A		1/2		1:1	
		REV		B	

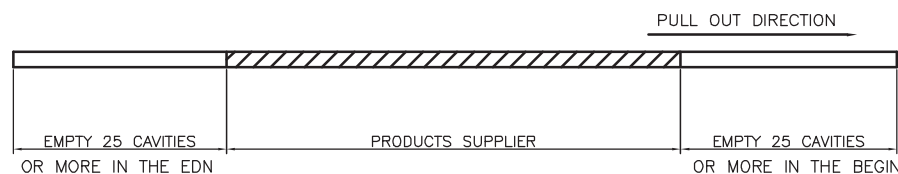
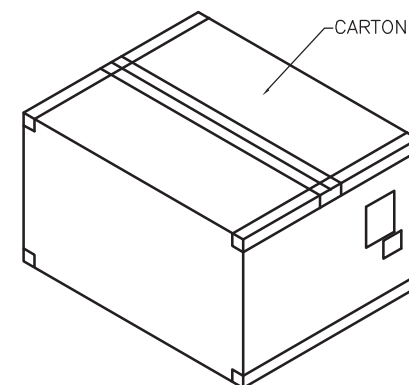
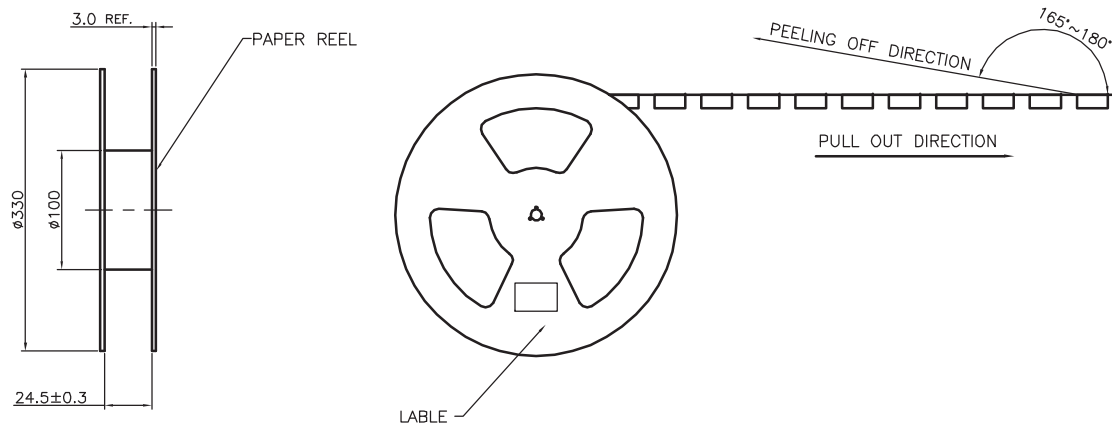
1.029A1-006-5R0	1.20
1.029A0-006-5R0	1.05
PART NO.	DIM A

A3

REV	ECN NO	DESCRIPTION	DATE	APPD
SEE SHEET 1/2				



- Notes:
- MATERIAL:
CARRIER TAPE: PS.
COVER TAPE: PE,PET,PEF
 - Q'TY: 2000PCS/REEL, 6000PCS/CARTON
 - PEELING FORCE: 10gf~130gf.



EXTEND USE		TITLE	
SIM CARD CONN.		LOW PROFILE SIM CARD CUSTOMER DRAWING	
UNIT mm		DWG NO	
MATERIAL		C-1.029A0	
QTY		P/N:	
FINISHED		SEE TABLE	
GENERAL TOLERANCE		SHEET SCALE	
DIMENSION		2/2 1:1	
ANGLES		REV	
±0.30 ±3'		B	
.0 ±0.25 .0 ±2'			
.00 ±0.20 .00 ±1'			
.000 ±0.10			